**Product data sheet** 

# 1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO263 (D2PAK) surface mountable plastic package intended for use in applications requiring very high inrush current capability, high thermal cycling performance and high junction temperature capability ( $T_{i(max)} = 150$  °C).

### 2. Features and benefits

- · AC power control
- · High blocking voltage capability
- High thermal cycling performance
- · Planar passivated for voltage ruggedness and reliability
- High immunity to false turn-on by dV/dt
- High junction operating temperature capability (T<sub>j(max)</sub> = 150 °C)
- Surface mountable package
- · Package meets UL94V0 flammability requirement
- · Package is RoHS compliant
- · IEC 61000-4-4 fast transient

# 3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation
- Protection circuit in Power Supplies for Consumer / Industrial / Medical Equipment

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
$V_{DRM}$	repetitive peak off-state voltage			800		V	
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave; $T_{mb} \le 134 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3		30			А
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 10 ms; Fig. 4; Fig. 5		350			А
		half sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 8.3 \text{ ms}$		385			Α
T <sub>j</sub>	junction temperature			-40 to 150		0	°C
Symbol	Parameter	Conditions	Notes	Min Typ Max		Max	Unit
Static cha	racteristics						
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$		6	-	15	mA
I <sub>H</sub>	holding current	$V_D = 12 \text{ V}; T_j = 25 \text{ °C}; Fig. 9$		-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>τ</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>		-	1.30	1.50	V
Dynamic	characteristics						
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_{j}$ = 150 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit			-	V/µs	

SCR

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	А	anode		A   K G
3	G	gate		sym037
mb	A	mounting base; connected to anode	TO-263 (D2PAK)	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
TYN30B-800T	TO263	TYN30B-800TJ	Reel	800	TO263N	26-Sep-2016

# 7. Marking

### Table 4. Marking codes

Type number	Marking codes
TYN30B-800T	TYN30B 800T

# 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage			800	V
$V_{RRM}$	repetitive peak reverse voltage			800	V
$\mathbf{I}_{T(AV)}$	average on-state current	half sine wave; T <sub>mb</sub> ≤ 134 °C;		19	А
$I_{T(RMS)}$	RMS on-state current	half sine wave; T <sub>mb</sub> ≤ 134 °C; Fig. 1; Fig. 2; Fig. 3		30	A
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4; Fig. 5		350	А
		half sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 8.3 ms		385	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10 ms; sine-wave pulse		612.5	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 30 mA		200	A/µs
I <sub>GM</sub>	peak gate current			5	А
$V_{GM}$	peak gate voltage			5	V
$V_{RGM}$	peak reverse gate voltage			7	V
$P_GM$	peak gate power			20	W
$P_{\text{G(AV)}}$	average gate power	over any 20 ms period		0.5	W
T <sub>stg</sub>	storage temperature			-40 to 150	°C
T <sub>j</sub>	junction temperature			-40 to 150	°C

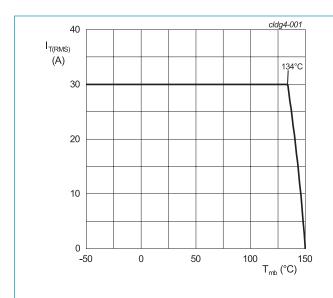
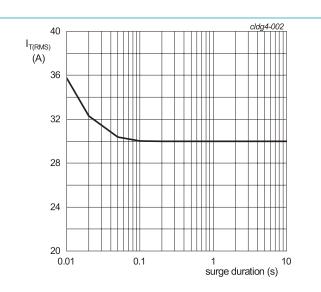
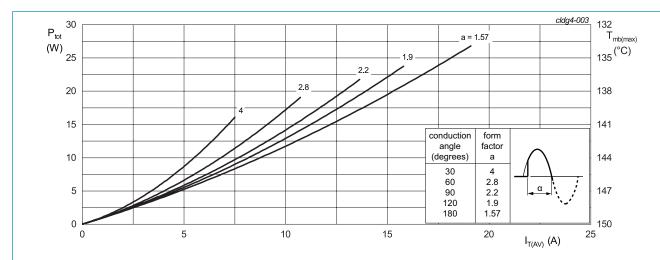


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T<sub>mb</sub> = 134 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values

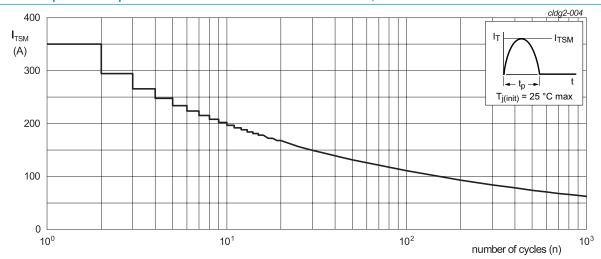
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 $\alpha$  = conduction angle

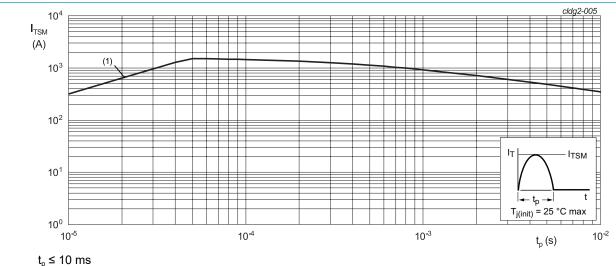
a = form factor =  $I_{T(RMS)}/I_{T(AV)}$ 

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



(1) dl<sub>T</sub>/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

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## 9. Thermal characteristics

### **Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 6		-	-	0.6	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air		-	55	-	K/W

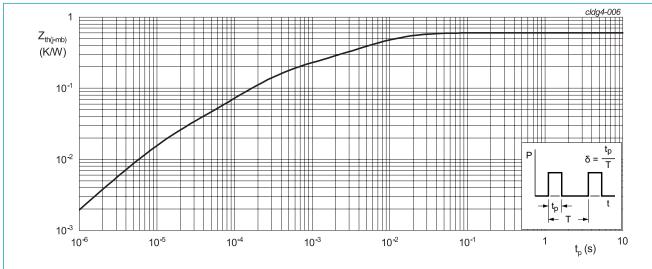


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

# 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	racteristics						•
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$		6	-	15	mA
IL	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 8$		-	-	80	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>		-	-	60	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>		-	1.30	1.50	V
$V_{\rm GT}$	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 ^{\circ}\text{C}; Fig. 11$		-	0.6	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C		0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 25 °C		-	-	0.5	μA
		V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C		-	-	1	mA
I <sub>R</sub>	reverse current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 25 °C		-	-	0.5	μA
		V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C		-	-	1	mA
Dynamic	characteristics						
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 536 V; $T_j$ = 150 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit		500	-	-	V/µs
t <sub>gt</sub>	gate-controlled turn-on time	$I_{TM} = 30 \text{ A}; V_D = 800 \text{ V}; I_G = 100 \text{ mA};$ $dI_G/dt = 5 \text{ A}/\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	2	-	μs
t <sub>q</sub>	commutated turn-off time	$V_{DM}$ = 536 V; $T_j$ = 150 °C; $I_{TM}$ = 30 A; $V_R$ = 25 V; $dI_T/dt$ = 30 A/µs; $dV_D/dt$ = 50 V/µs		-	70	-	μs

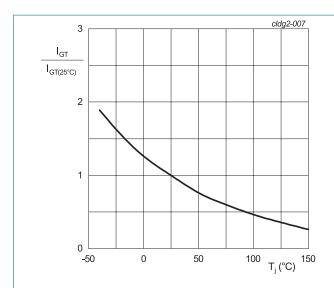


Fig. 7. Normalized gate trigger current as a function of junction temperature

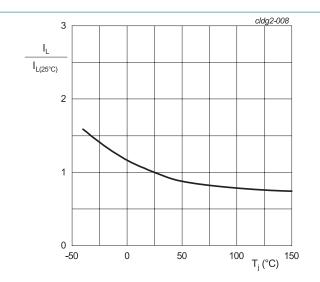


Fig. 8. Normalized latching current as a function of junction temperature

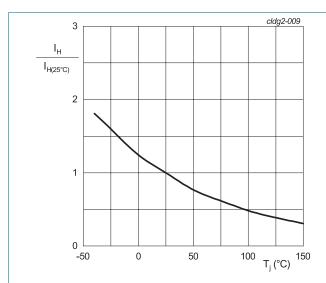
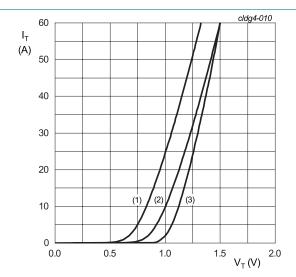


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o$  = 0.925 V;  $R_s$  = 0.0102 Ω (1)  $T_j$  = 150 °C; typical values (2)  $T_j$  = 150 °C; maximum values (3)  $T_j$  = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

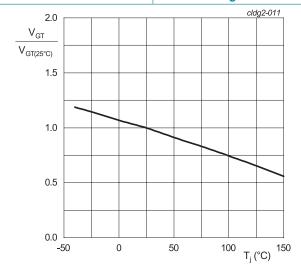
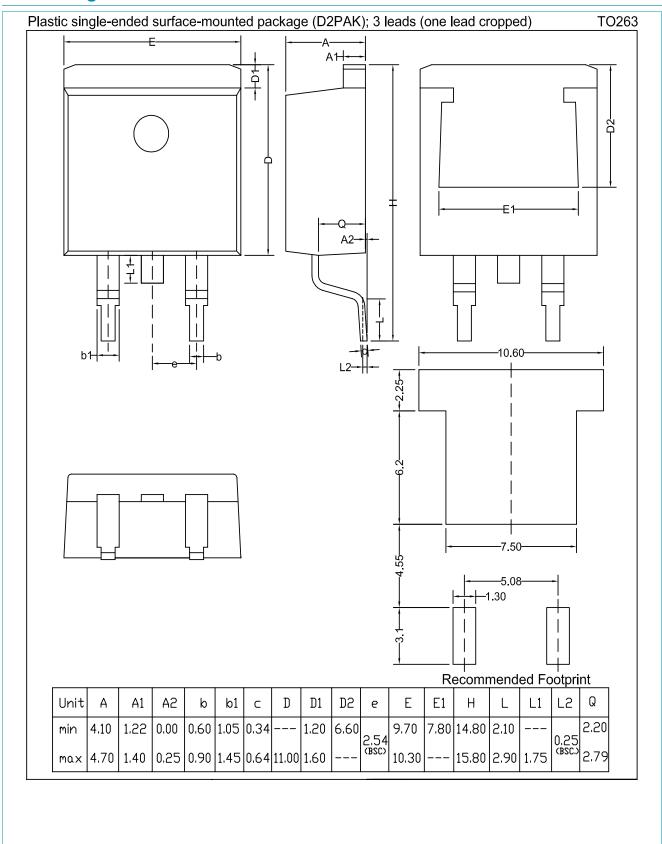


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

# 11. Package outline



## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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